

MATERIAL DECLARATION SHEET

BOURNS®

Material Number	CC322522A series			
Product Line	Wound Chip Inductor			
Compliance Date	2025/03/31			
RoHS Compliant	YES	MSL	1	

No.	Construction Element(subpart)	Homogeneous Material	Material weight [g]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Core	Ferrite	0.01	Iron oxide (Fe ₂ O ₃)	1309-37-1	66.0%	13.2	20
				Nickel oxide (NiO)	1313-99-1	8.00%	1.60	
				Zinc oxide (ZnO)	1314-13-2	22.0%	4.40	
				Copper oxide(CuO)	1317-38-0	4.00%	0.80	
2	Wire	Copper	0.0095	Copper(Cu)	7440-50-8	99.95%	18.99	20
				Misc. ,not to declare	/	0.05%	0.01	
		Resin	0.0005	Polyesterimide	37317-16-1	100.0%	1.00	
3	Terminal	Copper	0.019	Copper (Cu)	7440-50-8	100.0%	38.00	40
		plating-Sn	0.001	Tin (Sn)	7440-31-5	100.0%	2.00	
4	Adhesive	Epoxy	0.002	Bisphenol A diglycidyl ether	25068-38-6	72.0%	2.88	4
				Polyacrylic acid; 2-Propenoic acid homopolymer; A	9003-01-4	1.00%	0.04	
				Titanium Dioxide	13463-67-7	2.00%	0.08	
				Silicon dioxide	14808-60-7	25.0%	1.00	
5	Molding Compound	Resin	0.004	silica	60676-86-0	69.0%	5.52	8
				Antimony(III) oxide	1309-64-4	2.50%	0.20	

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				Formaldehyde, polymer with 2-(chloromethyl)oxirane and 2-methylphenol	29690-82-2	15.0%	1.20	
				Phenol-Formaldehyde Resin	9003-35-4	10.0%	0.80	
				Brominated epoxy resin	40039-93-8	2.50%	0.20	
				Carbon black	1333-86-4	1.00%	0.08	
6	Solder Wire	Tin	0.002	Tin (Sn)	7440-31-5	100.0%	4.00	4
7	Solder Bar	Tin	0.002	Tin (Sn)	7440-31-5	100.0%	4.00	4
		Total weight	0.05					

This Document was updated on: 2025/03/31

Important remarks:

1. It is the responsibility of the user to verify they are accessing the latest version.